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TO THE HONORABLE DIRECTOR OF THE UNITED STATES PATENT AND TRADEMARK OFFICE. PLEASE RECORD THE ATTACHED ORIGINAL DOCUMENTS OR COPY THEREOF.

1. Name of conveying parties:

CHOUNG, Jong-Hyun PARK, Hong-Sick
YOUN, Joo-Ae HONG, Sun-Young
KIM, Bong-Kyun SHIN, Won-Suk
LEE, Byeong-Jin

Additional name(s) of conveying party(ies) attached?

Yes No

2. Name and address of receiving party:

Name: SAMSUNG ELECTRONICS CO., LTD.
Address: 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea

Additional name(s) of receiving party(ies) attached?

Yes No

3. Nature of Conveyance:

Assignment Merger
Security Agreement Change of Name
Other

Execution Date: November 19, 2007

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: November 19, 2007

A. Patent Application No.(s)

Title: THIN FILM TRANSISTOR ARRAY AND METHOD OF MANUFACTURING THE SAME

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: David W. Heid
Internal Address: MACPHERSON, KWOK CHEN & HEID LLP
Street Address: 2033 Gateway Place, Suite 400
City San Jose State CA Zip 95110

6. Total number of applications and patents involved: One (1)

7. Total fee (37 CFR 3.41): \$40.00

Authorized to be charged to Deposit Account No. 50-2257.
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8. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

David W. Heid, Reg. No. 25,875
Name of Person Signing

Signature

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PATENT
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ASSIGNMENT

For good and valuable consideration, receipt of which is hereby acknowledged, we,

Jong-Hyun CHOUNG	of	816-1702, Hansin Apt., Byeokjeokgol 8-danji Apt., Yeongtong-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Korea
Hong-Sick PARK	of	202-1003, Hyundai I-Park Apt., Mangpo-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Korea
Joo-Ae YOUN	of	211-902, Maehwa maeul Jugong 2-danji Apt., Yatap-dong, Bundang-gu, Seongnam-si, Gyeonggi-do, Korea
Sun-Young HONG	of	410-1006, Saechunnyun Greenville 4-danji., Singal-dong, Giheung-gu, Yongin-si, Gyeonggi-do, Korea
Bong-Kyun KIM	of	Na-103, Samwoo., #546-1, Juan 2-dong, Nam-gu, Incheon, Korea
Won-Suk SHIN	of	201-1304, LG Village 2-cha., Seongbok-dong, Yongin-si, Gyeonggi-do, Korea
Byeong-Jin LEE	of	107-1502, Yeokbuk maeul Sinseong Apt., Yeokbuk-dong, Yongin-si, Gyeonggi-do, Korea

hereby sell, assign and transfer to **Samsung Electronics Co., Ltd.** A corporation, having a place of business at #416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea, its successors and assigns, the entire right, title and interest throughout the world in my invention in

THIN FILM TRANSISTOR ARRAY AND METHOD OF MANUFACTURING THE SAME

for which I have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; I authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from me; I agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and I request that the United States Patent and Trademark Office issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 19 day of _____, 2007.

Jong - Hyun CHOUNG
Jong-Hyun CHOUNG

WITNESSED:

Signature

Date

Type or print name of witness

Executed this 17 day of _____, 2007.

Hong-Sick PARK
Hong-Sick PARK

WITNESSED:

Signature

Date

Type or print name of witness

Executed this 19 day of _____, 2007.

Joo Ae Youn
Joo-Ae YOUN

WITNESSED:

Signature

Date

Type or print name of witness

Executed this 19 day of November, 2007.

Sun-Young Hong
Sun-Young HONG

WITNESSED:

Signature

Date

Type or print name of witness

Executed this 17 day of 11, 2007.

Bong-Kyun Kim
Bong-Kyun KIM

WITNESSED:

Signature

Date

Type or print name of witness

Executed this 19 day of 11, 2007.

won - Suk shin
Won-Suk SHIN

WITNESSED:

Signature

Date

Type or print name of witness

Executed this 19 day of _____, 2007.

Lee, Byeong Jin
Byeong-Jin LEE

WITNESSED:

Signature

Date

Type or print name of witness